

HOSTAFORM®

POM copolymer Antistatical modified; very easy flowing Injection molding type; the antistatical effect improves, when the molded part absorbs enough humidity; good chemical resistance to solvents, fuel and strong alkalis as well as good hydrolysis resistance; high resistance to thermal and oxidative degradation. Hostaform C 27021 AS is suggested for dissipation of minor buildup of static electricity. However, it is not intended for use in fuel system components where static dissipation is critical to part performance. Please refer to Celanese's ESD (electrostatic dissipative) grades for those applications.

Preliminary Datasheet

Product information		
Resin Identification	POM	ISO 1043
Part Marking Code	>POM<	ISO 11469
Rheological properties		
Melt volume-flow rate	25 cm ³ /10min	ISO 1133
Temperature	190 °C 2.16 kg	
Load Moulding shrinkage, parallel	2.16 kg 1.9 %	ISO 294-4, 2577
Moulding shrinkage, normal	1.8 %	ISO 294-4, 2577
Typical mechanical properties		
Tensile modulus	2650 MPa	ISO 527-1/-2
Tensile stress at yield, 50mm/min	62 MPa	ISO 527-1/-2
Tensile strain at yield, 50mm/min Nominal strain at break	8 % 20 %	ISO 527-1/-2 ISO 527-1/-2
Charpy notched impact strength, 23°C	20 % 5 kJ/m²	ISO 527-17-2 ISO 179/1eA
Charpy notched impact strength, -30°C	4.5 kJ/m ²	ISO 179/1eA
Ball indentation hardness, H 358/30	147 MPa	ISO 2039-1
Poisson's ratio	0.38 ^[C]	
[C]: Calculated		
Thermal properties		
Melting temperature, 10 °C/min	166 °C	ISO 11357-1/-3
Coefficient of linear thermal expansion (CLTE), parallel	110 E-6/K	ISO 11359-1/-2
Electrical properties		
Surface resistivity	1E12 Ohm	IEC 62631-3-2
Physical/Other properties		
Density	1410 kg/m ³	ISO 1183
Injection		
Drying Recommended	no	
Drying Temperature	100 °C	
Drying Time, Dehumidified Dryer Processing Moisture Content	3-4 h ≤0.2 %	
Melt Temperature Optimum	≤0.2 % 200 °C	
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Min. melt temperature	190 °C
Max. melt temperature	210 °C
Screw tangential speed	≤0.3 m/s
Mold Temperature Optimum	100 °C
Min. mould temperature	80 °C
Max. mould temperature	120 °C
Hold pressure range	60 - 120 MPa

Characteristics

Processing	Injection Moulding
Delivery form	Pellets
Additives	Release agent
Special characteristics	Static dissipative

Additional information

Injection molding

Preprocessing

General drying is not necessary due to low moisture absorption of the resin.

In case of bad storage conditions (water contact or condensed water) the use of a recirculating air dryer (100 to 120 $^{\circ}$ C / max. 40 mm layer / 3 to 6 hours) is recommended.

Max. Water content 0,2 %

Processing

Standard injection moulding machines with three phase (15 to 25 D) plasticating screws will fit.

Postprocessing

Conditioning e.g. moisturizing is not necessary.

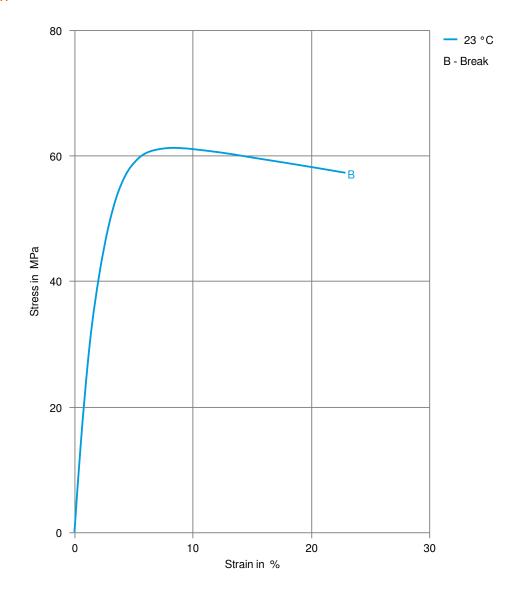
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Stress-strain

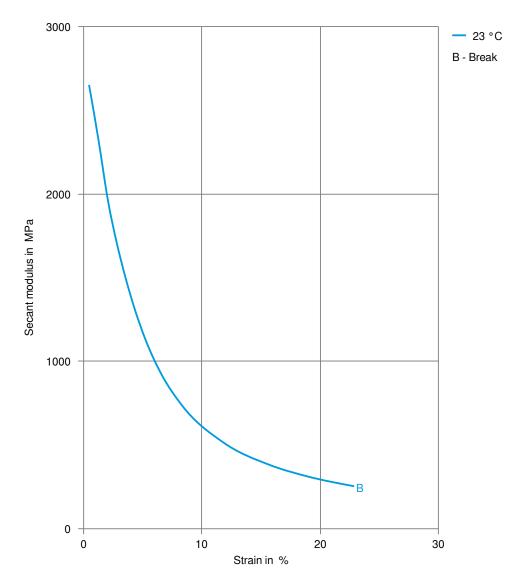






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Secant modulus-strain



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Page: 4 of 4

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